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1. (Amended) A semiconductor substrate stock/transfer vessel, which is an openable/closeable sealed vessel used in a semiconductor device manufacturing process and adapted to store or transfer a semiconductor substrate,

*A1*

wherein said vessel incorporates at least one adsorbent capable of adsorbing on organic substance, and said adsorbent is mounted detachably, and wherein said at least one adsorbent is at least one of an ion-exchange resin and a material with a surface having an Si-F bond.

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5. (Amended) A semiconductor substrate stock/transfer vessel, which is an openable/closeable sealed vessel used in a semiconductor device manufacturing process and adapted to store or transfer a semiconductor substrate,

*A2*

wherein said vessel incorporates at least one adsorbent capable of adsorbing on organic substance, and said adsorbent is mounted detachably and wherein said adsorbent is a silicon wafer with a surface having a Si-F bond.

10. (Amended) A method of manufacturing a semiconductor device wherein a semiconductor substrate is stored in a stock/transfer vessel incorporating at least one adsorbent capable of adsorbing an organic substance during an operation wait time between respective steps of manufacturing said semiconductor device, said adsorbent being mounted detachably, and wherein said at least one adsorbent is selected to be at least one of an ion-exchange resin and a material with a surface having an Si-F bond.

*A3*

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15. (Amended) A method of manufacturing a semiconductor device wherein a semiconductor substrate is stored in a stock/transfer vessel incorporating at least one adsorbent capable of adsorbing an organic substance during an operation wait time